

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. KOMATSU, et al.
Serial No.: 10/594,548
Filed: SEPTEMBER 27, 2006
For: HEAT-RESISTANT PHOTSENSITIVE RESIN
COMPOSITION, METHOD FOR FORMING PATTERN USING
THE COMPOSITION, AND ELECTRONIC PART
Group AU: 1795
Examiner: John S. Y. Chu
Confirm. No.: 3540

AMENDMENT

Mail Stop: AMD – NO FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

December 14, 2010

Sir:

In response to the Office Action mailed September 14, 2010, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.